# Lecture 5: Cost, Price, and Price for Performance 

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## Review From Last Time

- Given sales a function of performance relative to competition, tremendous investment in improving product as reported by performance summary
- Good products created when have:
- Good benchmarks
- Good ways to summarize performance
- If benchmarks/summary inadequate, then choice between improving product for real programs vs. improving product to get more sales; sales almost always wins!
- Execution time is the REAL measure of computer performance!
- What about cost?


## Impact of Means on SPECmark89 for IBM 550

Ratio to VAX: Time: Weighted Time:

| Program | Before | After | Before | After | Before | After |
| :--- | ---: | ---: | ---: | ---: | ---: | ---: |
| gcc | 30 | 29 | 49 | 51 | 8.91 | 9.22 |
| espresso | 35 | 34 | 65 | 67 | 7.64 | 7.86 |
| spice | 47 | 47 | 510 | 510 | 5.69 | 5.69 |
| doduc | 46 | 49 | 41 | 38 | 5.81 | 5.45 |
| nasa7 | 78 | 144 | 258 | 140 | 3.43 | 1.86 |
| li | 34 | 34 | 183 | 183 | 7.86 | 7.86 |
| eqntott | 40 | 40 | 28 | 28 | 6.68 | 6.68 |
| matrix300 | 78 | 730 | 58 | 6 | 3.43 | 0.37 |
| fpppp | 90 | 87 | 34 | 35 | 2.97 | 3.07 |
| tomcatv | 33 | 138 | 20 | 19 | 2.01 | 1.94 |
| Mean | 54 | 72 | 124 | 108 | 54.42 | 49.99 |
|  | Geometric | Arithmetic | WeightedArith. |  |  |  |
|  | Ratio | 1.33 | Ratio | 1.16 | Ratio | 1.09 |

## Integrated Circuits Costs

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Wafer cost<br>Dies per Wafer * Die yield

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Final test yield
Die cost $=\frac{\text { Wafer cost }}{\text { Dies per Wafer * Die yield }}$
Dies per wafer $=\frac{\pi^{*}(\text { Wafer_diam } / 2)^{2}}{\text { Die Area }}-\frac{\pi^{*} \text { Wafer_diam }}{\sqrt{2^{*} \text { Die Area }}}$

- Test dies



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Die Yield = Wafer yield *


## Integrated Circuits Costs



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Die Yield $=$ Wafer yield * $\left\{1+\frac{\text { Defects_per_unit_area * Die_Area }}{\alpha}\right\}^{-\alpha}$
Die Cost goes roughly with die area ${ }^{4}$

## Real World Examples

| Chip $\begin{gathered}\text { Met } \\ \text { lay }\end{gathered}$ |  | Line width | Wafer cost | Defect $/ \mathrm{cm}^{2}$ | Area $\mathrm{mm}^{2}$ | Dies/ wafer | Yield Die Cost |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| 386DX | 2 | 0.90 | \$900 | 1.0 | 43 | 360 | 71\% | \$4 |
| 486DX2 | 3 | 0.80 | \$1200 | 1.0 | 81 | 181 | 54\% | \$12 |
| PowerPC 601 | 4 | 0.80 | \$1700 | 1.3 | 121 | 115 | 28\% | \$53 |
| HP PA 7100 | 3 | 0.80 | \$1300 | 1.0 | 196 | 66 | 27\% | \$73 |
| DEC Alpha | 3 | 0.70 | \$1500 | 1.2 | 234 | 53 | 19\% | \$149 |
| SuperSPARC | 3 | 0.70 | \$1700 | 1.6 | 256 | 48 | 13\% | \$272 |
| Pentium | 3 | 0.80 | \$1500 | 1.5 | 296 | 40 | 9\% | \$417 |

- From "Estimating IC Manufacturing Costs," by Linley Gwennap, Microprocessor Report, August 2, 1993, p. 15


## Other Costs

## Die Test Cost $=$ Test Jig Cost * Ave. Test Time Die Yield

Packaging Cost: depends on pins, heat dissipation, beauty, ...

| Chip | Die <br> cost |  |  |  | Package |  |  | pins | type | cost | Test \& | Tssembly | Total |
| :--- | ---: | ---: | ---: | ---: | ---: | ---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| 386DX | $\$ 4$ | 132 | QFP | $\$ 1$ | $\$ 4$ | $\$ 9$ |  |  |  |  |  |  |  |
| 486DX2 | $\$ 12$ | 168 | PGA | $\$ 11$ | $\$ 12$ | $\$ 35$ |  |  |  |  |  |  |  |
| PowerPC 601 | $\$ 53$ | 304 | QFP | $\$ 3$ | $\$ 21$ | $\$ 77$ |  |  |  |  |  |  |  |
| HP PA 7100 | $\$ 73$ | 504 | PGA | $\$ 35$ | $\$ 16$ | $\$ 124$ |  |  |  |  |  |  |  |
| DEC Alpha | $\$ 149$ | 431 | PGA | $\$ 30$ | $\$ 23$ | $\$ 202$ |  |  |  |  |  |  |  |
| SuperSPARC | $\$ 272$ | 293 | PGA | $\$ 20$ | $\$ 34$ | $\$ 326$ |  |  |  |  |  |  |  |
| Pentium | $\$ 417$ | 273 | PGA | $\$ 19$ | $\$ 37$ | $\$ 473$ |  |  |  |  |  |  |  |

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- Component Costs



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- Gross Margin (add 82\% to 186\%) nonrecurring costs: R\&D, marketing, sales, equipment maintenance, rental, financing cost, pretax profits, taxes



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- Direct Costs (add $25 \%$ to $\mathbf{4 0 \%}$ ) recurring costs: labor, purchasing, scrap, warranty
- Gross Margin (add $82 \%$ to $186 \%$ ) nonrecurring costs: R\&D, marketing, sales, equipment maintenance, rental, financing cost, pretax profits, taxes
- Average Discount to get List Price (add $33 \%$ to $66 \%$ ): volume discounts and/or retailer markup



## Chip Prices (August 1993)

- Assume purchase 10,000 units

| Chip | Area <br> $\mathrm{mm}^{2}$ | Mfg. <br> cost | Price | Multi- <br> plier | Comment |
| :--- | ---: | ---: | ---: | ---: | :--- |
| 386DX | 43 | $\$ 9$ | $\$ 31$ | 3.4 | Intense Competition |
| 486DX2 | 81 | $\$ 35$ | $\$ 245$ | 7.0 | No Competition |
| PowerPC 601 | 121 | $\$ 77$ | $\$ 280$ | 3.6 |  |
| DEC Alpha | 234 | $\$ 202$ | $\$ 1231$ | 6.1 | Recoup R\&D? |
| Pentium | 296 | $\$ 473$ | $\$ 965$ | 2.0 | Early in shipments |

## Workstation Costs: \$1000 to \$3000

- DRAM:
- Color Monitor:
- CPU board:
- Hard disk:
- CPU cabinet:
- Video \& other I/O:
- Keyboard, mouse:

50\% to 55\%
15\% to 20\%
10\% to 15\%
8\% to 10\%
3\% to 5\%
3\% to 7\%
1\% to 2\%

## Learning Curve



## Volume vs. Cost

- Rule of thumb on applying learning curve to manufacturing:
"When volume doubles, costs reduce 10\%"
A DEC View of Computer Engineering by C. G. Bell, J. C. Mudge, and J. E. McNamara, Digital Press, Bedford, MA., 1978.
- 40 MPPs @ 200 nodes = 8,000 nodes/year vs. 100,000 Workstations/year

$$
12.5 X \approx 2^{3.6}=>(0.9)^{3.6}=0.68
$$

Cost should be $1 / 3$ less for same components

- What about PCs vs. WS?


## Volume vs. Cost: PCs vs. Workstations

|  | 1990 | 1992 | 1994 | 1997 |
| :--- | ---: | ---: | ---: | ---: |
| PC | $23,880,898$ | $33,547,589$ | $44,006,000$ | $65,480,000$ |
| WS | 407,624 | 584,544 | 679,320 | 978,585 |
| Ratio | 59 | 57 | 65 | 67 |

- $65 X \approx 2^{6.0}=>(0.9)^{6.0}=0.53$
$\approx 50 \%$ costs for whole market for PCs vs. Workstations

Single company: 20\% WS market vs. 10\% PC market
$\begin{array}{lllll}\text { Ratio } 29 & 29 & 32 & 33\end{array}$

- $32 X \approx 2^{5.0}=>(0.9)^{5.0}=0.59$
$\approx 60 \%$ costs for single company for PCs vs. Workstations


## High Margins on High-End Machines

- R\&D considered return on investment (ROI) $\approx 10 \%$
- Every \$1 R\&D must generate $\$ 7$ to $\$ 13$ in sales
- High end machines need more \$ for R\&D
- Sell fewer high end machines
- Fewer to amortize R\&D
- Much higher margins
- Cost of 1 MB Memory (January 1994):

| PC | $\$ 40$ | (Mac Quadra) |
| :--- | :--- | :--- |
| WS | $\$ 42$ | (SS-10) |
| Mainframe | $\$ 1920$ | (IBM 3090) |
| Supercomputer | $\$ 600$ | (M90 DRAM) |
|  | $\$ 1375$ | (C90 15 ns SRAM) |

## Recouping Development Cost on Low Volume Microprocessors?

- Hennessy says MIPS R4000 cost $\$ 30 \mathrm{M}$ to develop
- Intel rumored to invest $\$ 100 \mathrm{M}$ on 486
- SGI/MIPS sells 300,000 R4000s over product lifetime?
- Intel sells 50,000,000 486s?
- Intel must get \$100M from chips (\$2/chip)
- SGI/MIPS can get \$30M from margin of workstations vs. chips vs. $\$ 100 / c h i p$
- Alternative: SGI buys chips vs. develops them


## Price/Performance Gross Margin vs. Market Segment



## Price/Performance Gross Margin vs. Market Segment



## Impact of Margin Shrink on Society/Computer Industry

- Economy?
- Research Labs?
- Future Products?
- Your jobs?


## Information Technology R\&D

U.S. IT's Biggest R\&D Spenders in 1993: Total \$29.2 billion

| $\square$ IBM | $\square$ AT\&T | $\square$ HP | $\square$ DEC |
| :--- | :--- | :--- | :--- |
| $\square$ Motorola | $\square$ Intel | $\square$ Xerox | $\square$ Apple |
| $\square$ GM-H.E. | $\square$ Texas Instr | $\square$ Unisys | $\square$ Microsoft |
| $\square$ Sun | $\square$ Tandem | $\square$ Honeywell | $\square$ 297 other companies |



## Accelerating Pace of Product Development



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## Shift in Employment Towards Software and Services



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## Long Term R\&D Investments Take Time to Payoff



## US IT Trade Balance (It’s Negative!)

## IT Industry Exports and Trade Balance (\$, Billions)



RHK.S96 29

